



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20240829000.1
Qualify OPA607IDBVR/T with additional bond wire
Change Notification / Sample Request**

Date: August 29, 2024

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20240829000.1

Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA607IDBVR	NULL
OPA607IDBVT	NULL

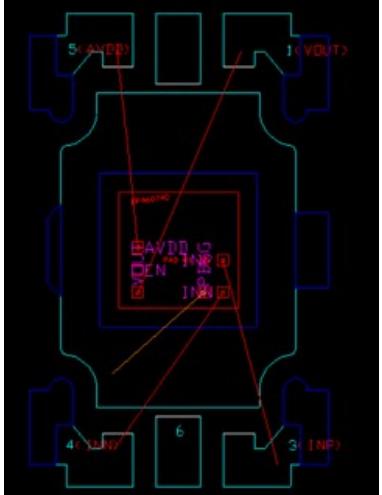
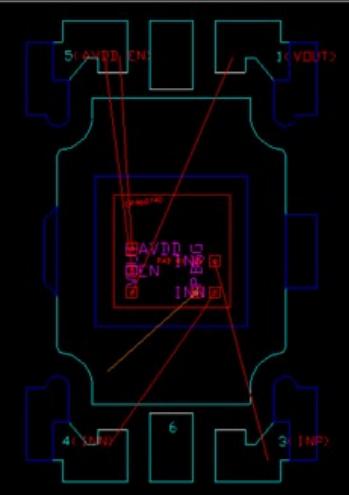
Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN#20240829000.1	PCN Date:	August 29, 2024
Title:	Qualify OPA607IDBVR/T with additional bond wire		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	November 27, 2024	Sample requests accepted until:	September 28, 2024*
*Sample requests received after September 28, 2024 will not be supported.			
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/>	Wafer Fab Material
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of OPA607IDBVR/T for additional bond wire between the VCC pin and Enable pad. Construction differences are as follows:

	Current	Proposed
Bond Diagram		
Enable pad to pin 5	No Wire	Single Wire

Reason for Change:

Supply continuity

The pull-up functionality is being strengthened by tying the Enable pad directly to VCC for the 5-pin DBV which does not have an external Enable pin. This ensures the device does not enter a low power state as a result of a process shift in the on-die pull-up resistor.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

None

Product Affected:

OPA607IDBVR	OPA607IDBVT
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Qualification Report

Approve Date 08-JULY -2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: OPA607IDBVT	QBS Product Reference: OPA607IDCKR	QBS Product Reference: OPA607IDBVR	QBS Process/Package Reference: TLV9001IDBVR	QBS Package Reference: OPA990IDBVR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	1/77/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	3/9/0
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	1/3/0	-	1/3/0	-
ESD	E2	ESD HBM	-	3000 Volts	-	1/3/0	-	1/3/0	3/9/0
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-	1/3/0	3/9/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	1/30/0	1/30/0	3/90/0
WB	-	Wire Pull	-	-	1/76/0	-	-	-	-

QBS: Qual By Similarity

Qual Device OPA607IDBVT is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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